

SPECIFICATIONS

BGA 940

Mechanical

Contact Retention Force: 0.13kgf min.
Durability: 50 Cycles min.
Solder Ball Shear Force: 750gf min.
Unlatch Force: 240gf min.

BGA CPU Socket

BGA SMT Type

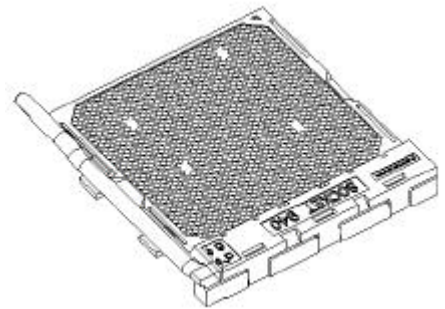
1.27X1.27mm [.05 X.05"] Pitch
940 Pos.

Electrical

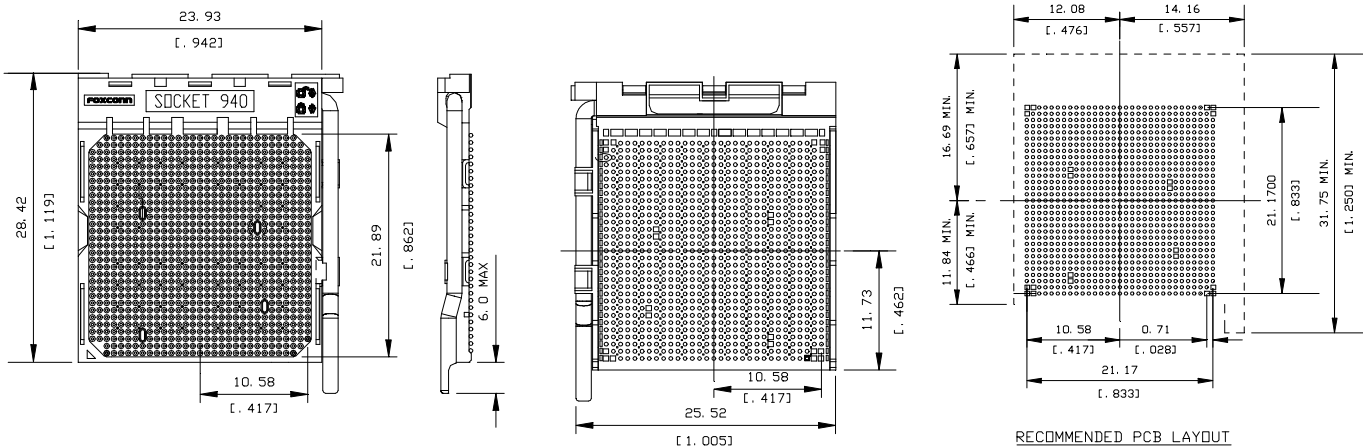
Contact Resistance : 25 mW max.
Insulation Resistance: 1000mW min.
Dielectric Withstanding Voltage: 650 VAC min.

Physical

Base: Thermoplastic, UL 94V-0 rated, Black Color
Cover: Thermoplastic, UL 94V-0 rated, Natural Color
Cam: Stainless Steel
Contact: Copper Alloy
Plating: See "ORDERING INFORMATION"
Operating Temperature: -40 to +105



DRAWING



ORDERING INFORMATION

PRODUCT NO.: P Z 9 4 0 0 3 - 3 1 4 6 - 0 3

- | | | |
|-------------------------------------|---|-----------------|
| Actual Loading | — | Pick-up Design |
| NO. of Pos. | — | 3=PI Film |
| 940=940 Pos. | — | Package |
| Solder Ball Type: | — | 0=Hard Tray |
| 0=Sn/Pb Type | — | Handle Design |
| Gold Plating On | — | 6=Metal Cam |
| Contact Area | — | Base Color |
| 3=30u" Gold Plating On Contact Area | — | 4=Black Color |
| | — | Grid Array Type |
| | — | 31=31X31 |